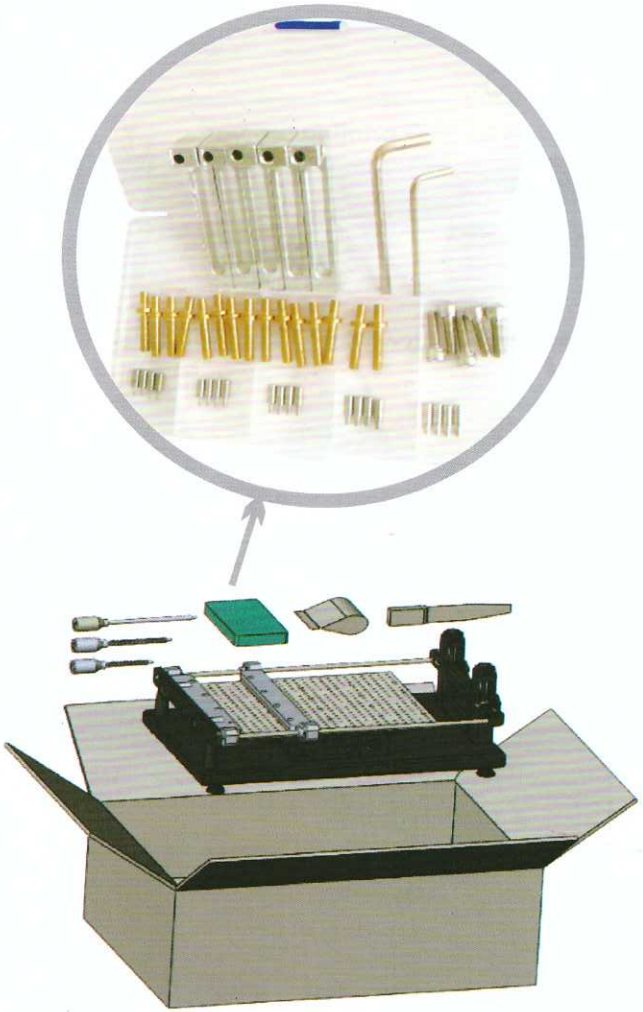
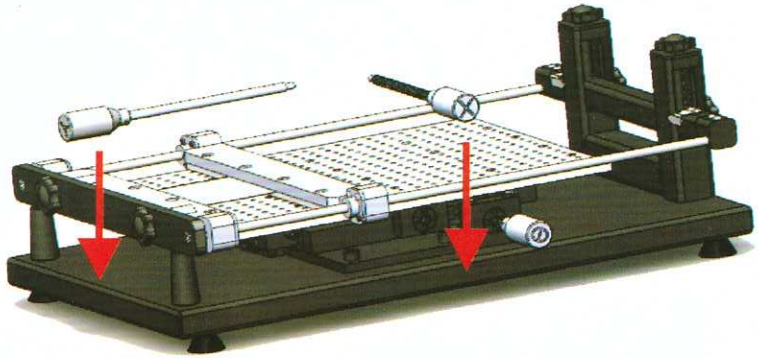
# FP2636 (Frameless Version) Unpacking Instructions

Accessories List

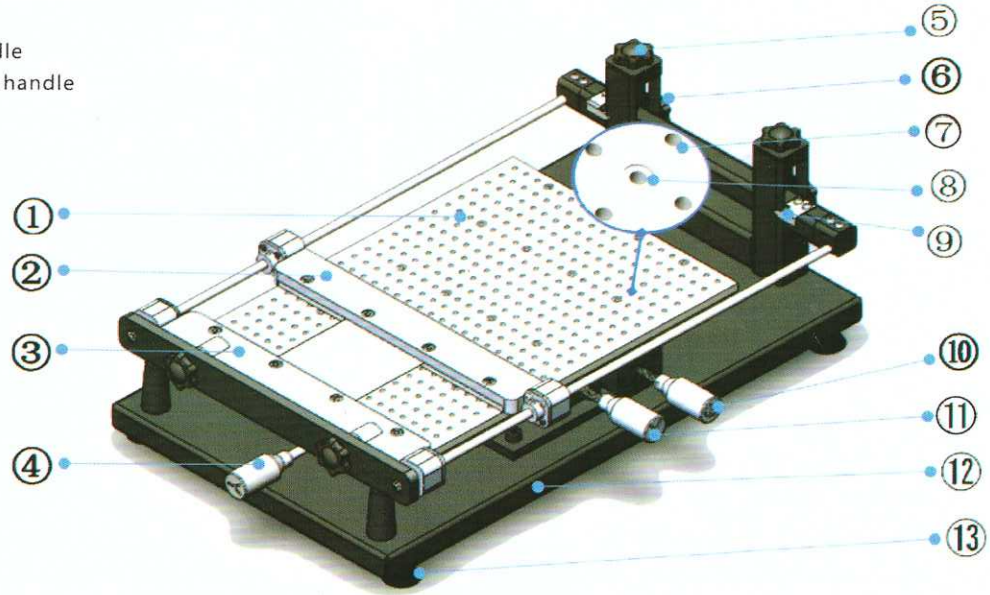


Install X,Y,θ handles to their positions accordingly.



## FP2636 Parts list

①: Porous positioning plate
②: Rear steel mesh fixed pressure plate
③: Front steel mesh fixed pressure plate
④: Y direction adjustment handle
⑤: Steel mesh height adjustment knob
⑥: Steel mesh height beam fixing knob
⑦: PCB top post placement hole
⑧: L-shaped fixing base screw hole
⑨: Height pointer
⑩: Angle adjustment handle
⑪: X direction adjustment handle
⑫: Printing table base
⑬: Printing table mats

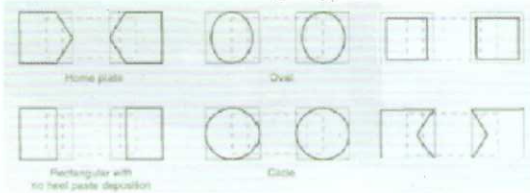


# FP2636 (Frameless Version)Printing Process Instructions

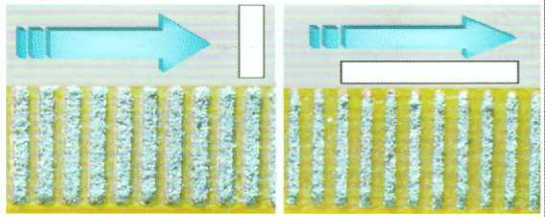
## Process Processes:

Prepare materials→Adjust the stencil printer→Stir solder paste→Place solder paste→Place the PCB and close the Stencil→Printing solder paste→Clean the Stencil

### Stencil for material preparation



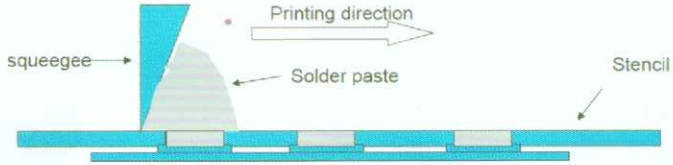
More and more micro components are used, how to take into account the amount of solder paste on large and small pads ; Contr olling the shape and size of the templat e opening is the most direct method

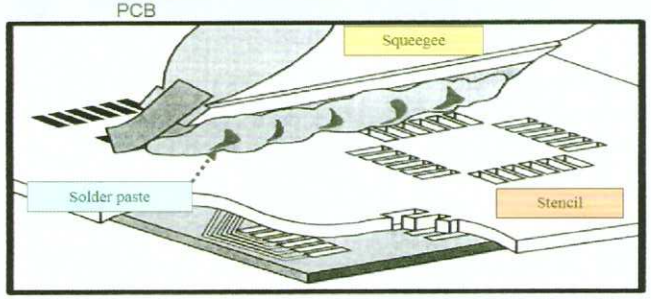


There is a big difference in the amount of solder paste in the parallel and vertical directions. When opening holes on the Stencil, the opening width in the parallel direction should be reduced accordingly.

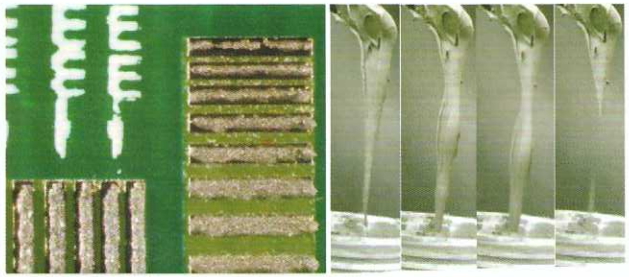
### Solder paste for material preparation

Unopened, reheated solder paste should be stored in the refrigerator when it is not used within 24hour s, the refrigeration temperatur e should be between 3℃and 8℃, do not reheat the solder paste of the same bottle more than twice.Before use, it must be taken out of the refrigerator and placed at room temperatur e for mor e than 4 hour s before it can be opened for use.



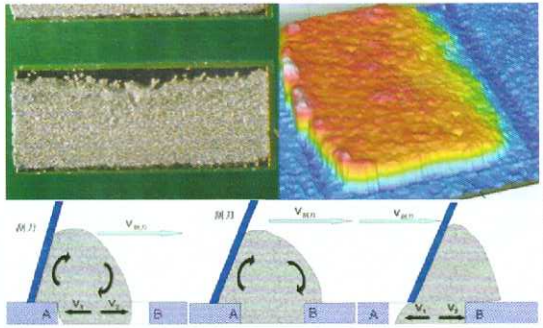




### Solder paste for SMT printing process



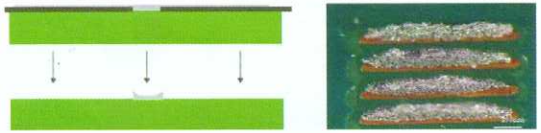
Before each addition the solder paste, the solder paste must be stirred uniformly before use,manual stirring speed is 2-3 seconds per revolution, in the same direction for 2 minutes to 5 minutes to make it into a fluid.The picture on the left is a typical printing abnormality caused by insufficient solder paste stirring.The picture on the right is a simple method for testing liquidity ( Picking up solder paste with a stirring knife can naturally fall )

### Printing for SMT printing process

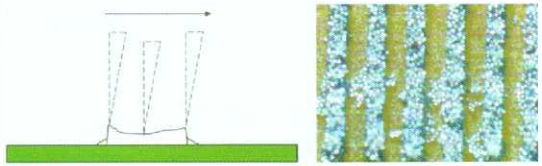


Solder paste does not roll, stencil holes filling is insufficient, solder paste is omission or defect.

### Cleaning for SMT printing process



The surface of the stencil is not thoroughly brushed clean, the solder paste is poorly formed, less solder paste, and lack of printing



Contaminated, Causes defects such as tin beads; poor solder paste molding,increased cleaning frequency.